

APPENDIX

CP-A Modifications for Dynamic RAM

ERRATA FOR CPA REV. 4 AND EARLIER  
ECN 77-0039

1. The following modification must be made to the CPA Rev. 4 or earlier Rev.'s if it is to be used with the RAM-16, RAM-32 or RAM-65 memory boards. This change makes the signal on backplane line 71 (RUN) agree with the bus definition. The change does not affect the CPA's compatability with other IMSAI products.
2. Refer to Figure 1 and make the following cut on the component side of the board.
  - (a) Cut the trace extending down from U24 pin 9.
3. Refer to Figure 2 and make the following cuts on the solder side of the board.
  - (a) Cut the trace from U24 pin 10 between this pin and feed through A.
  - (b) Cut the trace from feed through B near the spare IC location.
  - (c) Remove the entire pad of the feed through connected to edge connector pin 71.
4. Refer to Figure 2 and install the following jumpers on the solder side of the board.
  - (a) From U22 pin 5 to U24 pin 10.
  - (b) From edge connector pin 71 to U24 pin 9.
  - (c) From feed through A to feed through B.
5. Correct the schematic as shown in Figure 3.

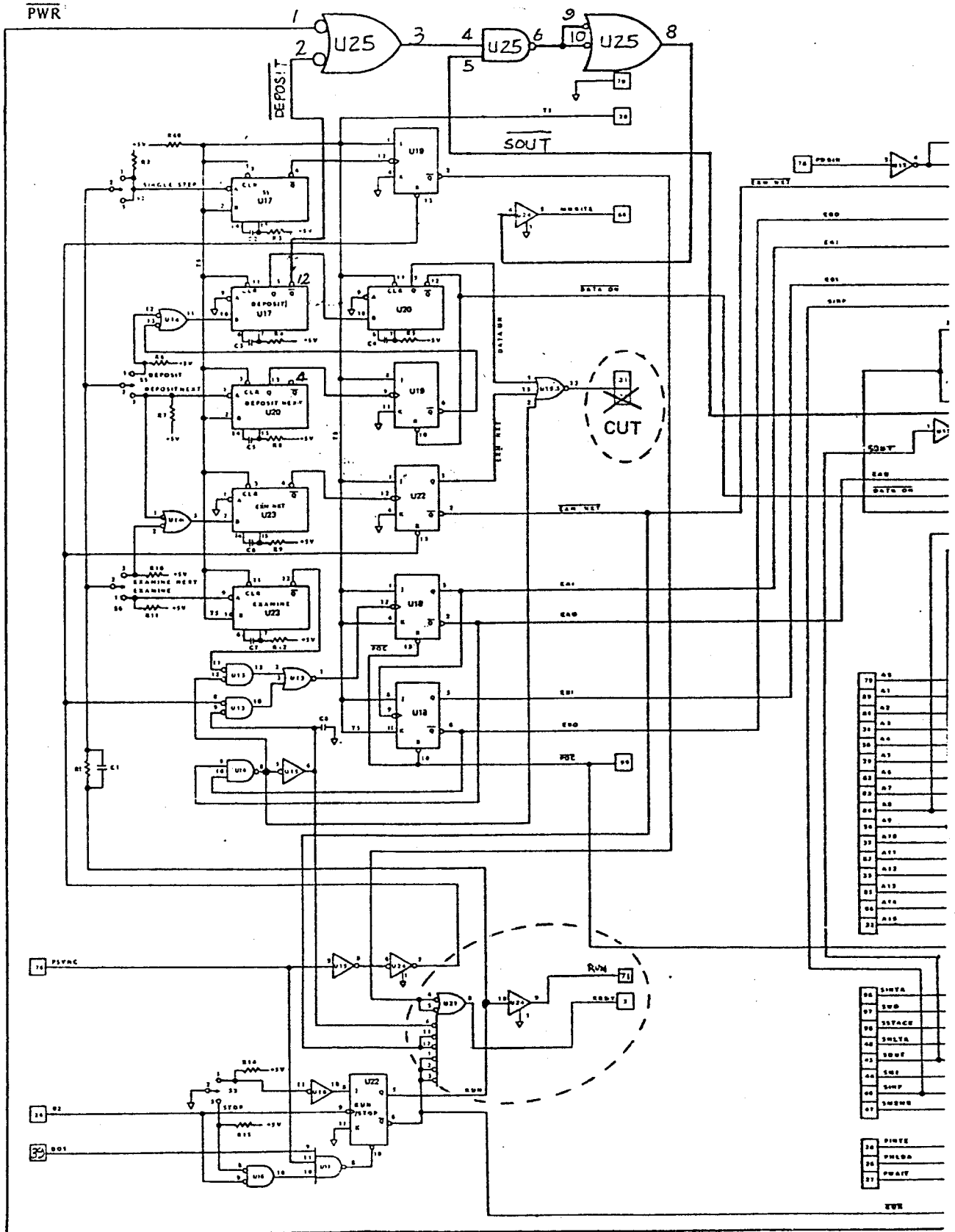
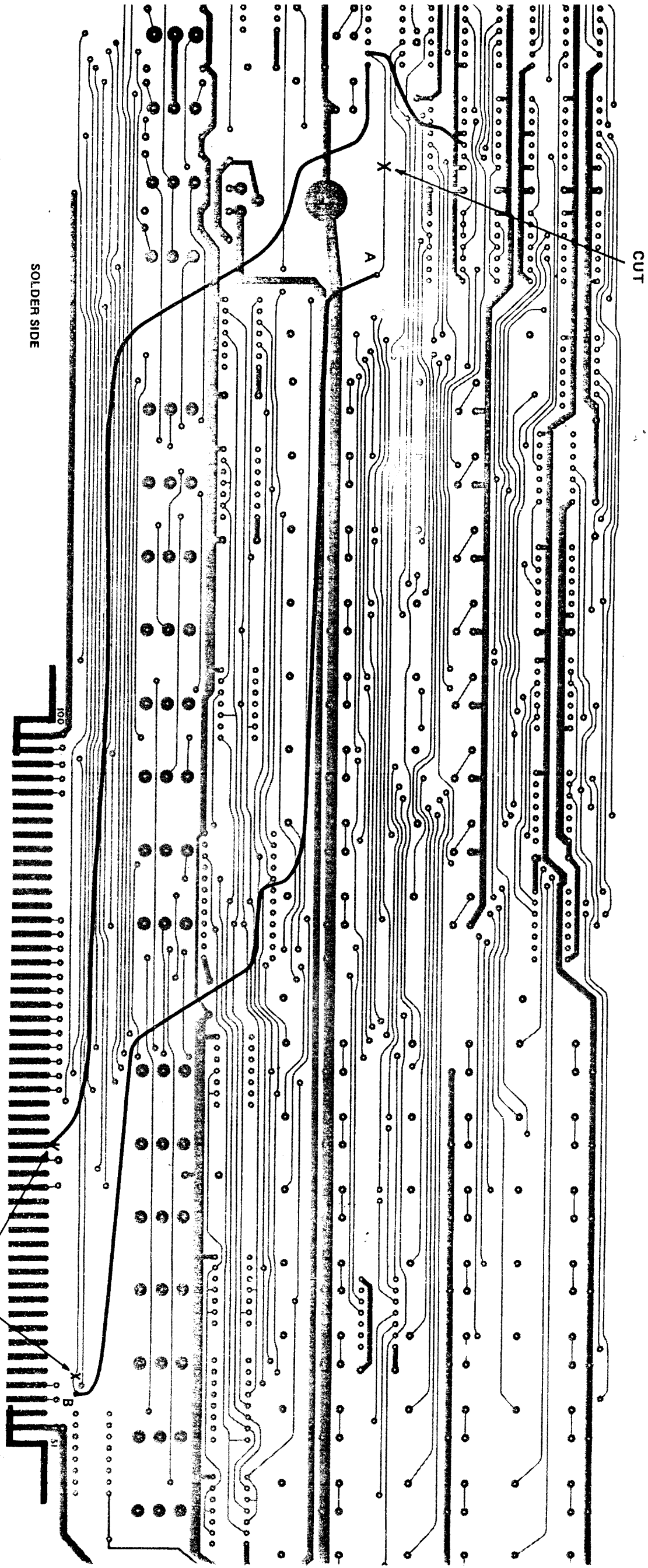


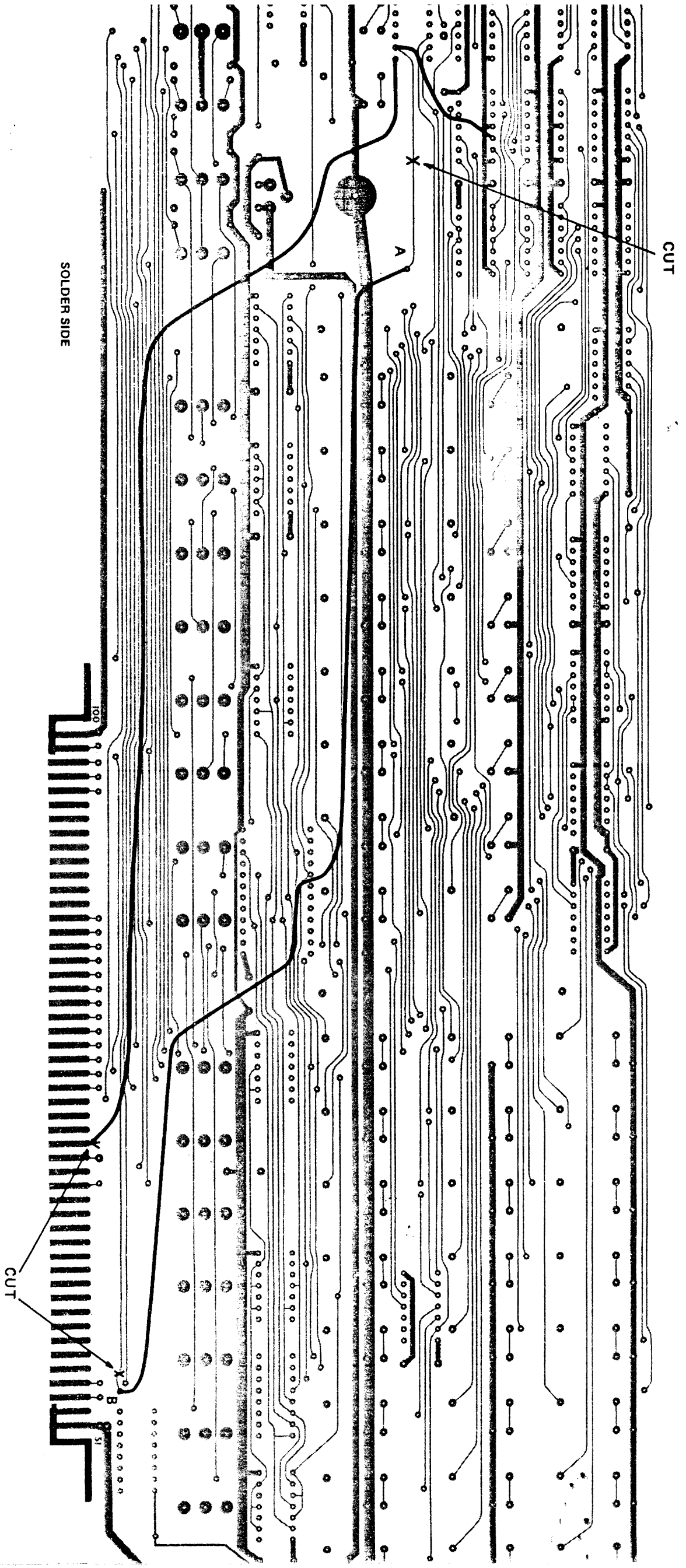
FIGURE 3  
 MODIFICATION TO CPA REV. 4 & EARLIER  
 ECN 77-0039



FG. CORP.  
 ANDRO, CA.  
 VED WORLDWIDE

TOLERANCES UNLESS OTHERWISE SPECIFIED	
FRACTIONS DEC.	±
ANGLES	±

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 FIGURE 2  
 MODIFICATION TO CPA REV. 4.0. E



SOLDER SIDE

CUT

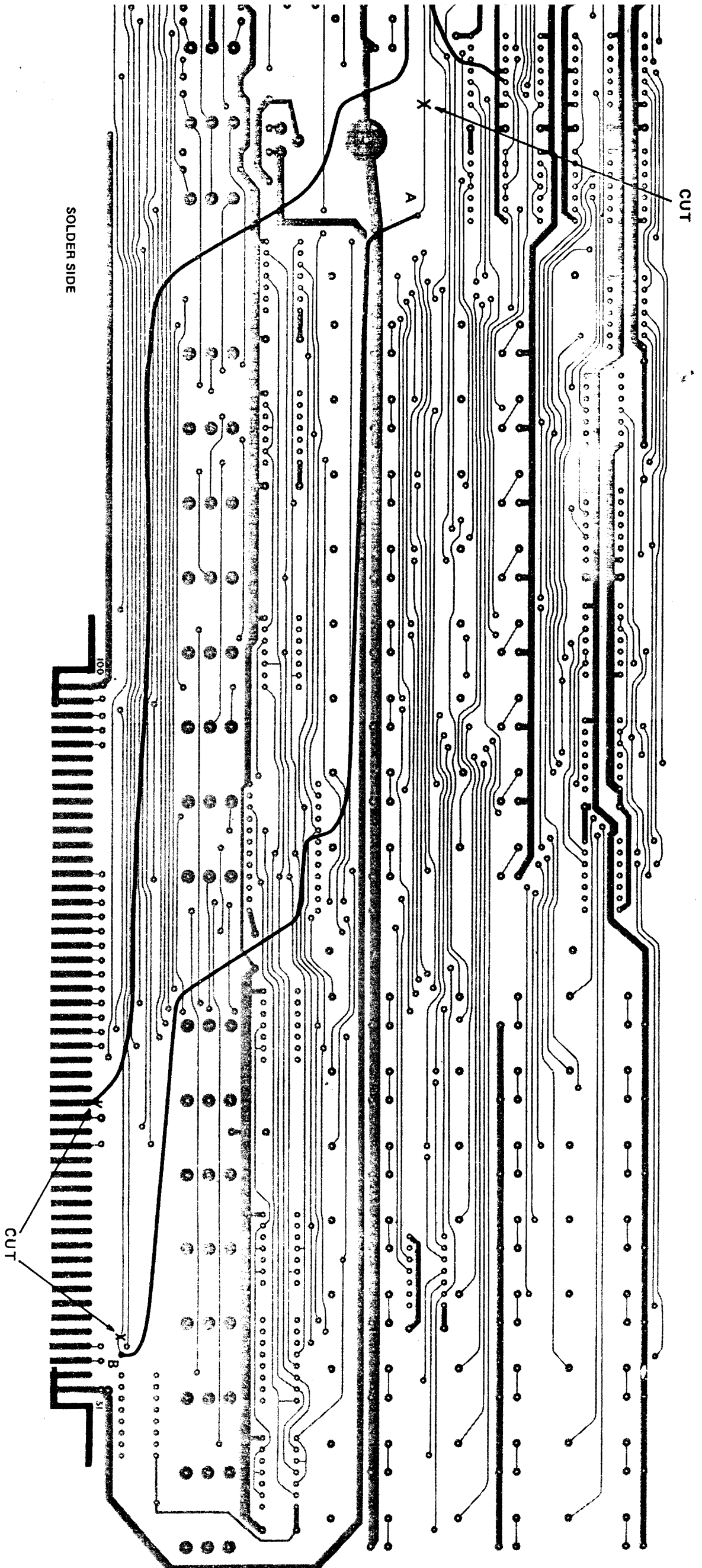
CUT

MFG. CORP.  
 ANDRO, CA.  
 RVED WORLDWIDE

TOLERANCES UNLESS OTHERWISE SPECIFIED	
FRACTIONS DEC. ANGLES	
±	±
±	±
±	±
APPROVAL DATE	

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FIGURE 2  
 MODIFICATION TO CPA REV. 4 & 5



SOLDER SIDE

CUT

CUT

MFG. CORP.  
LEANDRO, CA.  
SERVED WORLDWIDE

TOLERANCES UNLESS OTHERWISE SPECIFIED		
±	±	±
FRACTIONS	DEC.	ANGLES
APPROVALS	DATE	

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FIGURE 2  
MODIFICATION TO CPA REV. 4 & EARLIER  
FOR DYNAMIC DATA OPERATION